

Microfluidic Facility, Harvard Medical School

PROCEDURES FOR BONDING PDMS

Microfluidics Core Facility, Harvard Medical School

Sample cleaning

1. Punch the through-holes onto patterned PDMS slab for tubing connection.



2. Clean the PDMS surface with Isopropanol. Wipe the surface gently with foam-cotton swabs. Rinse in D.I. water and blow dry with compressed nitrogen.

Dry-run to set the bonding parameters for plasma etcher

- 3. Check that the inlet valves of O_2 and Ni are open (on the wall).
- 4. Turn on the vacuum pump.
- 5. Turn the **main power** on (red bottom).
- 6. Switch to open **vacuum** toggle switch (labeled as **VAC** in front panel). And check the throttle pressure on the display (around *0.100-0.350 torr* recommended).
- 7. Open **gas 1** toggle switch (oxygen) for 3-4 mins.
- 8. Adjust and stabilize the pressure at approximately **0.170-0.350 torr.**
- 9. Turn on the RF power switch and set the power at 100-110 Watts.
- 10. Turn off the **RF power.**
- 11. Turn off gas 1.
- 12. Turn off vacuum.
- 13. Switch to open **vent** toggle switch.
- 14. Wait until the door can be opened and turn off the **vent**.

Bonding Process

- 15. Load your samples. The surfaces needing treatment have to be face-up.
- 16. Turn on the **vacuum** toggle switch.
- 17. Turn on the **gas 1** switch.
- 18. Turn on the **RF power** toggle switch.
- 19. Expose the samples to plasma treatment for 10sec.
- 20. Turn off the **RF power.**

- 21. Turn off the gas 1.
- 22. Turn off the **vacuum** toggle switch.
- 23. Switch to open **vent** switch.
- 24. Wait until the pressure reaches 1torr and the door can be opened.
- 25. Turn off the **vent** switch.
- 26. Take the samples out and bond them in within 5 mins.



- 27. Put the bonded samples in oven of 65 degrees for 20mins in order to enhance bonding.
- 28. Test the bonding strength, trying to peel the layer off.



Front panel plasma etcher



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